



Lead free solder wire Flexsol 903

INTERFLUX®
ELECTRONICS N.V.



Technical data Flexsol 903
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Lead free, No-clean and halide free solder wire

Description:

Interflux® Flexsol 903

Lead-Free, No-Clean solder wire contains no halides and is recommended for **all class** (IPC-A-610) soldering.

It is designed to minimize flux spattering during soldering also at higher temperatures.

Flexsol 903 is designed to be used in both manual and automatic wire soldering applications.



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Key advantages:

- Very low spattering
- Classification to IPC and EN: **RO LO**
- Absolutely Halogen Free
- Long tip-life
- 3 flux channels
- Very good wetting on Cu, Ag, Sn ...
- Suited for automatic soldering

Availability

Flux type: IF 903

Flux content: 2,2% w/w — 3,5% w/w

alloy	melting point	diameters					
		0,35	0,50	0,70	1,00	1,50	2,00
Sn96,5Ag3Cu0,5	217°C—219°C	●	●	●	●	●	●
Sn99Ag0,3Cu0,7	217°C-227°C	●	●	●	●	●	●
Sn99,3Cu0,7	227°C	●	●	●	●	●	●

● = available



Work instructions

Manual soldering

The working temperature is between 320°C and 390°C. For more dense metals like Nickel, the temperature may be elevated to 420°C.

Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact surface with the component and

solder pad.

The use of a good soldering station is important in order to always have the correct temperature on the soldering joint. Use a soldering station with a response time as short as possible.

Heat up the surfaces of both component and island simultaneously. Slightly touch with the solder wire,

the point where component lead, soldering island and soldering tip meet (the small quantity of solder ensures a drastic lowering of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip. It is important that no solder wire is making contact with

the soldering tip during soldering to avoid flux spitting and premature flux consumption!

Handling

Storage

Store the solder wire in a clean environment between 0°C and 40°C

Handling

To avoid spool and wire damage, handle package with care



Test results

conform EN 61190-1-2(2002) and IPC J-STD-004A

Property	Result	Method
Chemical		
flux designator	RO L0	J-STD-004A
	W	EN61190-1-3 (2002)
	F-SW 31	DIN 8511
	1.1.1	ISO 9454
qualitative copper mirror	pass	J-STD-004A IPC-TM-650 2.3.32
	pass	TR-TSY-000078 13.1.6
qualitative halide silver chromate (Cl, Br)	pass	J-STD-004A IPC-TM-650 2.3.33D
	pass	TR-TSY-000078 13.1.4
spot test (F)	pass	J-STD-004A IPC-TM-650 2.3.35.1A
	pass	TR-TSY-000078 13.1.5
quantitative halide	0,00%	J-STD-004A IPC-TM-650 2.3.35C
Environmental		
SIR test	pass	J-STD-004A IPC-TM-650 2.6.3.3B
qualitative corrosion, flux	pass	J-STD-004A IPC-TM-650 2.6.15C



Packaging

Spools of 10g, 100g, 500g and 1000g

D i s c l a i m e r

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